Specifications for Wire Wound SMD Power Inductor

for Automotive Electronics

SPECIFICATIONS

Product Name		Wire Wound SMD Power Inductor				
Sunlord Part Nur	nper	ASW	PA4035S Series	S		
Customer Part N	umber					
Weight		228mg/pcs Typ.				
[⊠New Released		Revised] SPEC No.: ASWPA0702210000 es including specifications and appendix.]				
[This SPEC is total 1] [ROHS, Halogen-Free			and appendix.]			
A	Approved By	Checked By	Issued By	1		
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Idress: Sunlord Indust : 0086-755-29832333 For Customer approval	Fax: 0086-75	yuan Industrial Zono 55-82269029 E-M Date:	e, Guanlan, Shenzl ail: sunlord@sunlordir	hen, China 518110		
ddress: Sunlord Indust 1: 0086-755-29832333 For Customer approval of the customer approval of th	rial Park, Dafuy Fax: 0086-75 Only]	yuan Industrial Zono 55-82269029 E-M Date: Restricted	e, Guanlan, Shenzl ail: sunlord@sunlordir	hen, China 518110 nc.com		
ddress: Sunlord Indust 1: 0086-755-29832333 For Customer approval	Fax: 0086-75	yuan Industrial Zono 55-82269029 E-M Date: Restricted	e, Guanlan, Shenzl ail: sunlord@sunlordir	hen, China 518110		

Version Change History								
Rev.	Date	Item	Changed Contents	Change	Drawing	Check	Approval	
				Reasons				
01	/	/	/	New release	Yan Liu	Haigen He	Qintian Hou	
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1 Scope

1.1 Scope of parts

This specification applies to the ASWPA4035 Series of wire wound SMD power inductor for automotive electronics based on AEC-Q200D G1.

1.2 Scope of application

Product numbers recorded in this specification are limited to applications with the following modules:

Specifications for Wire Wound SMD Power Inductor

- (1) Multimedia system.
- (2) Prohibit using in Engine Control System.
- 1.3 Operating and storage temperature

The part temperature (ambient + temp. rise) should not exceed 125°C under worst case operating conditions. Circuit design, component placement, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

- 1) Operating and storage temperature range (individual chip without packing):-40°C ~+125°C (including self-heating)..
- 2) Storage temperature range (packaging conditions): -10 °C ~+40 °C and RH 70% (Max.)

2 Product Description and Identification (Part Number)

1) Description:

ASWPA4035 Series of Wire wound SMD power inductor.

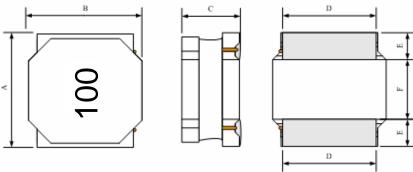
2) Product Identification (Part Number)

А	SWPA	4035	S	1R0	М	Т	Y01
1	2	3	4	(5)	6	7	8

①Feature Code	A: for Automotive
②Product Type	SWPA: Wire wound SMD power inductor
③External Dimensions(LxWxH) [mm]	4035: 4.0×4.0×3.5
④Feature type	S:Standard Type
⑤Nominal Inductance	1R0=1.0uH,100=10uH,101=100uH
⑥Inductance Tolerance	M: ±20%,N: ±30%
⑦Packing Code	T: Tape Carrier Package
Special Process code	Standard product is blank

3 Shape and Dimensions

Dimensions and recommended PCB pattern for reflow soldering, please see Fig.3-1, Fig. 3-2 and Table3-1.



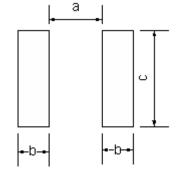


Fig.3-1

[Table 3-1] (Unit: mm)

Series	Α	В	С	D	E	а	b	С
ASWPA4035S	4.0±0.2	4.0±0.2	3.5±0.2	3.20±0.1	0.95±0.1	1.9Тур.	1.1Typ.	3.7Typ.

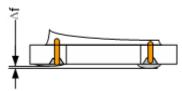


Fig.3-2

Δf: Clearance between terminal and the surface of plate must be 0.1mm max when coil is placed on a flat plate.

4 Electrical Characteristics

Customan		Inductance	Min.	D	С	Satur	ation	Heat F	Rating	
Customer P/N	Part Number	inductance	Self-resona	Resis	stance	Cur	rent	Cur	rent	Manhina
P/N		0.1MHz/1V	nt frequency	Max.	Тур.	Max.	Тур.	Max.	Тур.	Marking
	Units	μH	MHz	Ω	Ω	Α	Α	Α	Α	
	Symbol	L	SRF	DO	CR	Is	at	Irn	ns	-
	ASWPA4035SR47MT	0.47±20%	176	0.010	0.008	7.80	9.80	5.20	5.90	R47
	ASWPA4035SR68MT	0.68±20%	132	0.013	0.010	6.80	7.80	4.56	5.10	R68
	ASWPA4035S1R0MT	1.0±20%	121	0.024	0.020	6.30	6.90	3.85	4.50	1R0
	ASWPA4035S1R2MT	1.2±20%	70	0.028	0.023	6.00	6.70	3.60	4.20	1R2
	ASWPA4035S1R5MT	1.5±20%	60	0.030	0.025	5.20	6.10	3.30	3.90	1R5
	ASWPA4035S1R8MT	1.8±20%	52	0.034	0.028	4.60	5.50	3.20	3.70	1 R 8
	ASWPA4035S2R2MT	2.2±20%	52	0.040	0.033	4.30	4.80	3.00	3.50	2R2
	ASWPA4035S3R3MT	3.3±20%	38	0.058	0.048	3.50	3.80	2.50	2.90	3R3
	ASWPA4035S4R7MT	4.7±20%	31	0.082	0.068	3.00	3.20	2.10	2.45	4R7
	ASWPA4035S6R8MT	6.8±20%	24	0.101	0.084	2.50	2.80	1.90	2.20	6R8
	ASWPA4035S8R2MT	8.2±20%	26	0.112	0.093	2.10	2.40	1.80	2.10	8R2
	ASWPA4035S100MT	10.0±20%	21	0.14	0.12	2.00	2.30	1.55	1.85	100
	ASWPA4035S150MT	15.0±20%	16	0.23	0.19	1.60	1.80	1.25	1.45	150
	ASWPA4035S220MT	22.0±20%	10	0.29	0.24	1.30	1.50	1.10	1.30	220
	ASWPA4035S330MT	33.0±20%	10	0.42	0.35	1.10	1.30	0.90	1.05	330
	ASWPA4035S470MT	47.0±20%	8.4	0.59	0.49	0.95	1.05	0.75	0.90	470
	ASWPA4035S680MT	68.0±20%	7.0	1.09	0.91	0.75	0.85	0.55	0.65	680
	ASWPA4035S101MT	100±20%	5.6	1.38	1.15	0.65	0.75	0.45	0.55	101
	ASWPA4035S151MT	150±20%	4.0	2.28	1.90	0.50	0.55	0.35	0.45	151

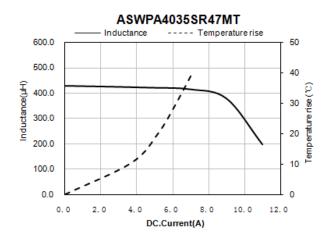
Note: * 1: Rated current: Isat (max.) or Irms (max.), whichever is smaller;

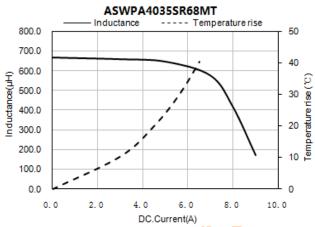
^{※ 2:} Saturation Current: Max. Value, DC current at which the inductance drops less than 30% from its value without current;
Typ. Value, DC current at which the inductance drops approximate 30% from its value without current;

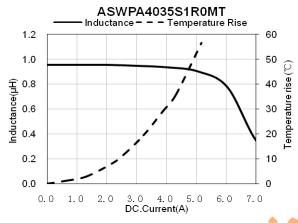
^{* 3:} Irms: DC current that causes the temperature rise (ΔT) from 20°C ambient.

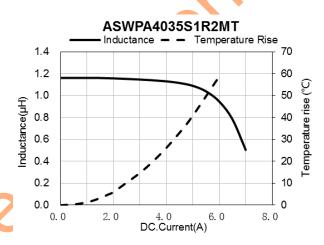
For Max. Value, $\Delta T < 40^{\circ}C$; For Typ. Value, ΔT is approximate $40^{\circ}C$.

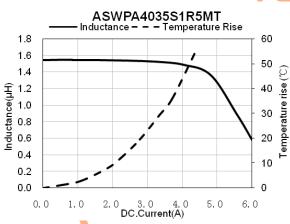
Appendix: Typical Electrical Characteristics:

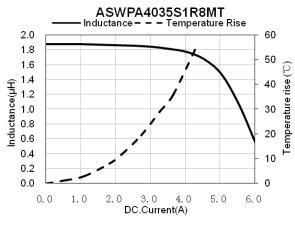


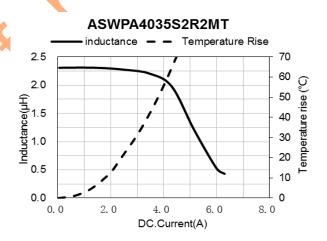


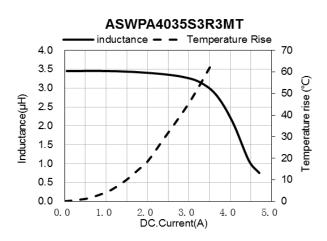


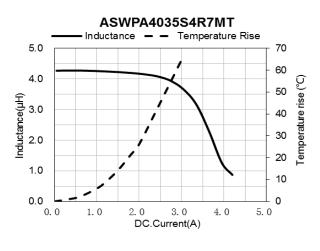


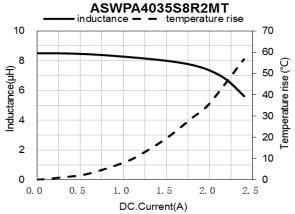


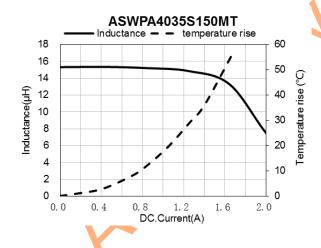


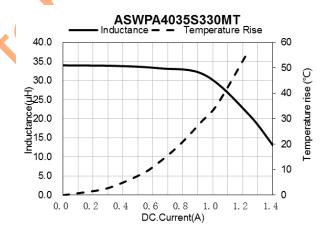


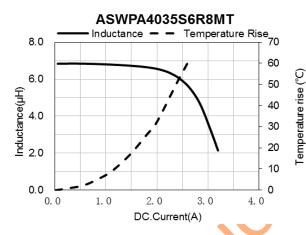


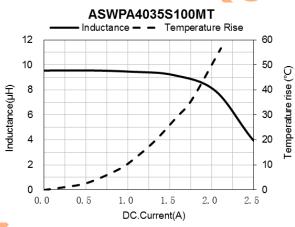


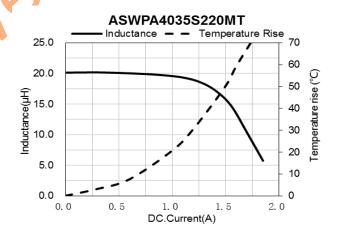


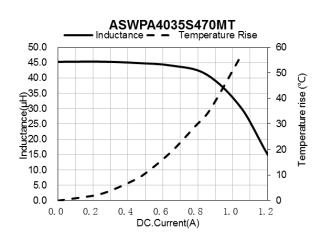


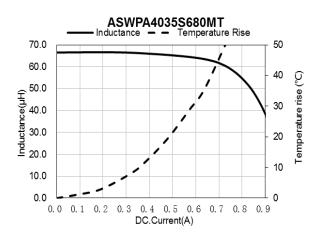


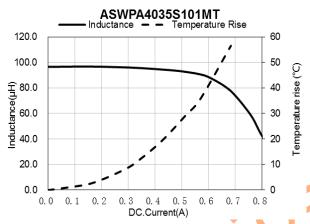


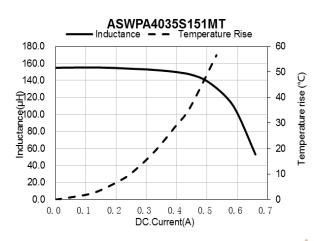












5 Test and Measurement Procedures

5.1 Test Conditions

5.1.1 Unless otherwise specified, the standard atmospheric conditions for measurement/test as:

a. Ambient Temperature: 20±15℃

b. Relative Humidity: 65±20%

c. Air Pressure: 86kPa to 106kPa

5.1.2 If any doubt on the results, measurements/tests should be made within the following limits:

a. Ambient Temperature: 20±2℃

b. Relative Humidity: 65±5%

c. Air Pressure: 86kPa to 106kPa

5.2 Visual Examination

Inspection Equipment: Visual.

5.3 Electrical Test

5.3.1 Inductance (L)

a. Refer to Item 4.Test equipment: WK3260B LCR meter or equivalent.

b. Test Frequency and Voltage: refers to **Item 4**.

5.3.2 Direct Current Resistance (DCR)

a. Refer to Item 4.

b. Test equipment: HIOKI 3540 or equivalent.

5.3.3 Saturation Current (Isat)

a. Refer to Item 4.

b. Test equipment: WK3260B LCR meter or equivalent.

5.3.4 Temperature rise current (Irms)

a. Refer to Item 4.

b. Test equipment (see Fig. 5.3.4-1, Fig. 5.3.4-2): Electric Power, Electric current meter, Thermometer.

c. Measurement method

1. Set test current to be 0 mA.

2. Measure initial temperature of choke surface.

3. Gradually increase current and measure choke temperature for corresponding current.

4. Definition of Temperature rise current: DC current that causes the temperature rise (ΔT) from ambient temperature.

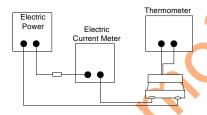


Fig. 5.3.4-1

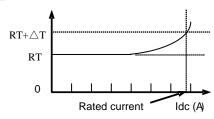


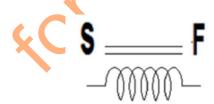
Fig. 5.3.4-2

5.3.5Self-resonant frequency(SRF)

a. Refer to Item 4.

b.Test equipment: Agilent E4991A+16197or equivalent

Schematic Diagram



6 Structure

The structure of ASWPA4035 product, please refer to Fig.6-1 and Table 6-1. 1)

Specifications for Wire Wound SMD Power Inductor

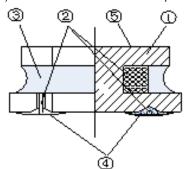


Fig. 6-1

[Table 6-1]

No.	Components	Material
1	Ferrite Core	NiZn Ferrite
2	Wire	Polyurethane system enameled copper wire
3	Magnetic Glue	Epoxy resin and magnetic powder
4	Electrodes	Ag/Ni/Sn+Cu +Sn Alloy
(5)	Marking	Laser Marking

Product Marking

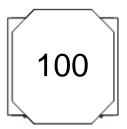


Fig. 7-1

	1—1N——	4 Electrodes	Ag/Ni/Sn+Cu +Sn Alloy				
		⑤ Marking	Laser Marking				
Fig. 6-1 7 Product Marking Please refer to Fig. 7-1. The content of marking please refers to Item 4.							
8 R	eliability Test						
No.	Test Item	Test Method(According to AEC-Q200)	Requirements				
1	Terminal Strength	Reflow 2 times,17.7N(Requirement from	No removal or split of the termination or other defects				
		AEC-Q200),X,Ydirect, 60(+1)s.	shall occur				
2	Resistance to Flexure	AEC-Q200),X,Ydirect, 60(+1)s. Reflow 2 times,2mm,60(+5)s.	shall occur No visible mechanical damage				
2	Resistance to Flexure Temp. Characteristics						
		Reflow 2 times,2mm,60(+5)s.	No visible mechanical damage				
		Reflow 2 times,2mm,60(+5)s40°C/15(+3)min→+25°C/15(+3)min →+125°C	No visible mechanical damage Inductance change should be within ±20% of reference				
3	Temp. Characteristics	Reflow 2 times,2mm,60(+5)s. -40°C/15(+3)min→+25°C/15(+3)min →+125°C /15(+3)min.	No visible mechanical damage Inductance change should be within ±20% of reference value measuring at 25°C				
3	Temp. Characteristics	Reflow 2 times,2mm,60(+5)s. -40°C/15(+3)min→+25°C/15(+3)min →+125°C /15(+3)min. Method 1:	No visible mechanical damage Inductance change should be within ±20% of reference value measuring at 25°C				
3	Temp. Characteristics	Reflow 2 times,2mm,60(+5)s. -40°C/15(+3)min→+25°C/15(+3)min →+125°C /15(+3)min. Method 1: ①pretreatment:155°C,4h	No visible mechanical damage Inductance change should be within ±20% of reference value measuring at 25°C				
3	Temp. Characteristics	Reflow 2 times,2mm,60(+5)s. -40°C/15(+3)min→+25°C/15(+3)min →+125°C /15(+3)min. Method 1: ①pretreatment:155°C,4h ②235°C,5(-0.5,+0)s.	No visible mechanical damage Inductance change should be within ±20% of reference value measuring at 25°C				
3	Temp. Characteristics	Reflow 2 times,2mm,60(+5)s. -40°C/15(+3)min→+25°C/15(+3)min →+125°C /15(+3)min. Method 1: ①pretreatment:155°C,4h ②235°C,5(-0.5,+0)s. ③Solder:Sn/3.0Ag/0.5Cu.	No visible mechanical damage Inductance change should be within ±20% of reference value measuring at 25°C Wetting shall be exceeded 95% coverage				
3	Temp. Characteristics	Reflow 2 times,2mm,60(+5)s. -40°C/15(+3)min→+25°C/15(+3)min →+125°C /15(+3)min. Method 1: ①pretreatment:155°C,4h ②235°C,5(-0.5,+0)s. ③Solder:Sn/3.0Ag/0.5Cu. Method 2: ①Steam aging:8h. ②235°C,5(-0.5,+0)s.	No visible mechanical damage Inductance change should be within ±20% of reference value measuring at 25°C Wetting shall be exceeded 95% coverage				
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3	Temp. Characteristics	Reflow 2 times,2mm,60(+5)s. -40°C/15(+3)min→+25°C/15(+3)min →+125°C /15(+3)min. Method 1: ①pretreatment:155°C,4h ②235°C,5(-0.5,+0)s. ③Solder:Sn/3.0Ag/0.5Cu. Method 2: ①Steam aging:8h. ②235°C,5(-0.5,+0)s. ③Solder:Sn/3.0Ag/0.5Cu. Method 3: ①Steam aging:8h.	No visible mechanical damage Inductance change should be within ±20% of reference value measuring at 25°C Wetting shall be exceeded 95% coverage Wetting shall be exceeded 95% coverage No more than 5% of the solderable termination exhibits exposed underlying, nonwettable base metal or				
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4	Temp. Characteristics	Reflow 2 times, 2mm,60(+5)s. -40°C/15(+3)min→+25°C/15(+3)min →+125°C /15(+3)min. Method 1: ①pretreatment:155°C,4h ②235°C,5(-0.5,+0)s. ③Solder:Sn/3.0Ag/0.5Cu. Method 2: ①Steam aging:8h. ②235°C,5(-0.5,+0)s. ③Solder:Sn/3.0Ag/0.5Cu. Method 3: ①Steam aging:8h. ②260°C,7(-0.5,+0.5)s. ③Solder:Sn/3.0Ag/0.5Cu.	No visible mechanical damage Inductance change should be within ±20% of reference value measuring at 25°C Wetting shall be exceeded 95% coverage Wetting shall be exceeded 95% coverage No more than 5% of the solderable termination exhibits exposed underlying, nonwettable base metal or				
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4	Temp. Characteristics Solderability	Reflow 2 times, 2mm,60(+5)s. -40°C/15(+3)min→+25°C/15(+3)min →+125°C /15(+3)min. Method 1: ①pretreatment:155°C,4h ②235°C,5(-0.5,+0)s. ③Solder:Sn/3.0Ag/0.5Cu. Method 2: ①Steam aging:8h. ②235°C,5(-0.5,+0)s. ③Solder:Sn/3.0Ag/0.5Cu. Method 3: ①Steam aging:8h. ②260°C,7(-0.5,+0.5)s. ③Solder:Sn/3.0Ag/0.5Cu.	No visible mechanical damage Inductance change should be within ±20% of reference value measuring at 25°C Wetting shall be exceeded 95% coverage Wetting shall be exceeded 95% coverage No more than 5% of the solderable termination exhibits exposed underlying, nonwettable base metal or metallization layers or portions of the ceramic substrate after exposure to molten solder				
4	Temp. Characteristics Solderability Resistance to	Reflow 2 times, 2mm,60(+5)s. -40°C/15(+3)min→+25°C/15(+3)min →+125°C /15(+3)min. Method 1: ①pretreatment:155°C,4h ②235°C,5(-0.5,+0)s. ③Solder:Sn/3.0Ag/0.5Cu. Method 2: ①Steam aging:8h. ②235°C,5(-0.5,+0)s. ③Solder:Sn/3.0Ag/0.5Cu. Method 3: ①Steam aging:8h. ②260°C,7(-0.5,+0.5)s. ③Solder:Sn/3.0Ag/0.5Cu.	No visible mechanical damage Inductance change should be within ±20% of reference value measuring at 25°C Wetting shall be exceeded 95% coverage Wetting shall be exceeded 95% coverage No more than 5% of the solderable termination exhibits exposed underlying, nonwettable base metal or metallization layers or portions of the ceramic substrate after exposure to molten solder (1) No visible mechanical damage				
3 4	Temp. Characteristics Solderability Resistance to Soldering Heat	Reflow 2 times, 2mm,60(+5)s. -40°C/15(+3)min→+25°C/15(+3)min →+125°C /15(+3)min. Method 1: ①pretreatment:155°C,4h ②235°C,5(-0.5,+0)s. ③Solder:Sn/3.0Ag/0.5Cu. Method 2: ①Steam aging:8h. ②235°C,5(-0.5,+0)s. ③Solder:Sn/3.0Ag/0.5Cu. Method 3: ①Steam aging:8h. ②260°C,7(-0.5,+0.5)s. ③Solder:Sn/3.0Ag/0.5Cu. Reflow:Max. 260°C/10s,3 times.	No visible mechanical damage Inductance change should be within ±20% of reference value measuring at 25°C Wetting shall be exceeded 95% coverage Wetting shall be exceeded 95% coverage No more than 5% of the solderable termination exhibits exposed underlying, nonwettable base metal or metallization layers or portions of the ceramic substrate after exposure to molten solder (1) No visible mechanical damage (2) Inductance change: Within ±10%				

Sun	nlord Specifica	tions for Wire Wound SMD Power Inductor	Categories: general confidential Page 11 of 17
7	Mechanical Shock	Half sine shock pulse,100g,6ms,6 shocks in each	(1) No visible mechanical damage
		3 mutually perpendicular directions (total of 18	(2) Inductance change: Within ±10%
		shocks).	
8	ESD Test	HBM ESD discharge waveform,8KV,each 1 time of	of (1) No visible mechanical damage
		+/-polarity.	(2) Inductance change: Within ±10%
9	Thermal Shock	Reflow 2 times, -40/(30±3min),+125/(30±3min),	(1) No visible mechanical damage
		transforming interval:20s(Max.),1000cycles.	(2) Inductance change: Within ±10%
10	Resistance to Low	Reflow 2 times,-40±2°C, 1000(+24) hours	(1) No visible mechanical damage
	Temperature		(2) Inductance change: Within ±10%
11	Resistance to High	Reflow 2 times,125±2°C,1000(+24)hours	(1) No visible mechanical damage
	Temperature		(2) Inductance change: Within ±10%
12	Moisture	Reflow 2 times,	(1) No visible mechanical damage
	Resistance	① 25℃→65℃,90%~100%RH,2.5h	(2) Inductance change: Within ±10%
		② 65℃,90%~100%RH,3h	
		③ 65℃→25℃,80%~100%RH,2.5h	
		④ 25°C→65°C,90%~100%RH,2.5h	
		⑤ 65℃,90%~100%RH,3h	
		⑥ 65℃→25℃,80%~100%RH,2.5h,	
		⑦ 25℃,90%~100%RH,8h,24hours of	. 0
		1cycle(total of 240 hours)	
13	Biased Humidity	Reflow 2 times,85 °C, 85%RH,1000h	(1) No visible mechanical damage
			(2) Inductance change: Within ±10%
14	Operational Life	Reflow 2 times,85±2°C,1000(+24)hours, rated	(1) No visible mechanical damage
		current	(2) Inductance change: Within ±10%
15	Flammability	Refer to UL94.	① t1 or t2:≤10s;
		X	② t1 plus t2 for the 5 specimens:≤50s;
			③ t2+t3 for each specimen:≤30s;
			④ No after-flame or after-glow of any specimen up to
			the holding clamp
			⑤ No cotton indicator ignited by flaming particles or
	i e		•

drops

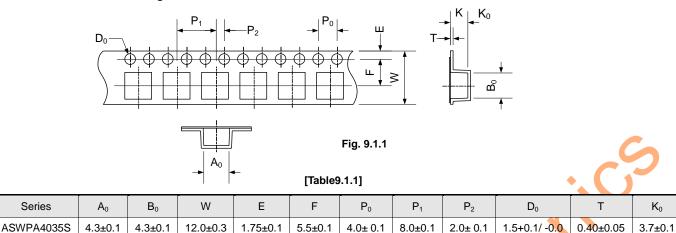
Packaging, Storage and Transportation

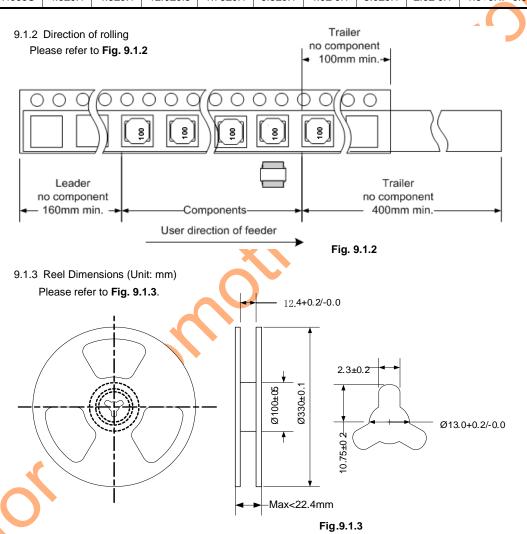
9.1 Tape and Reel Packaging Dimensions

9.1.1Taping Dimensions (Unit: mm)

Please refer to Fig. 9.1.1 and Table 9.1.1.

Specifications for Wire Wound SMD Power Inductor





Peel-off strength: 10~130gf.

Peel-off angle: 165°~180° refers to Fig.9.1.4.

Specifications for Wire Wound SMD Power Inductor

Peel-off speed: 300mm/min.

9.1.5 The number of components

A tape & reel package contains 2000 inductors.

9.1.6The allowable number of empty chip cavities

Maximum two (2) chip cavities missing product may exist in a reel but they may not be consecutive two cavities.

165°~180°

Fig. 9.1.4

Top cover tape

9.2 Packing Documents and Marking

9.2.1 Packing Documents

Packing documents include the following:

- Packaging list
- 2) Certificate of compliance (COC)
- 9.2.2Packing QTY.
 - Inner Box: 1 reel in each box. 1)
 - 2) Outer Box:2 or 4 inner boxes in each outer case.
 - 3) 2 or 4 reels in each outer case.
- 9.2.3Marking

1) Marking label information on reels includes (see Fig.9.2.3-1~2):

Fig.9.2.3-2a: Shipping labels

- P/O No. a).
- Customer Part No. b).
- c). Sunlord Part No.
- Quantity.. a).
 - b). Lot No.
- Date code
 - b). Inspection stamp

MFG address as 'Made In China'.

Fig.9.2.3-2b: Production label

- a). P/O No.
- b). Quantity...
- Lot No. c).
- Inspe No
- Inspection stamp
- MFG address as 'Made In China'.
- sequence number

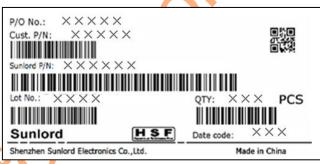


Fig.9.2.3-2a

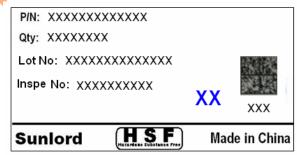
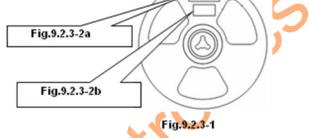
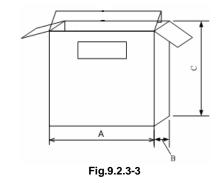


Fig.9.2.3-2b



Packaging type A(mm) B(mm) C(mm) Inner box 340 30 340

[Table 9.2.3-1]



[Table 9.2.3-2]

Packaging type	L(mm)	W(mm)	H(mm)
TYP1	380	380	250
TYP2	380	380	190

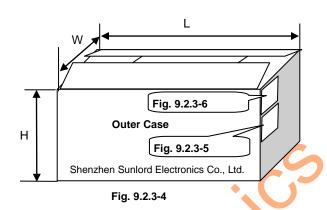
- 2)Marking label information on inner box
 - a). Inner box please refers to Fig.9.2.3-3 and Table 9.2.3-1.
 - b). Marking Label on inner box N/A.
- 3)Marking on outer case (see Fig.9.2.3-4~6):

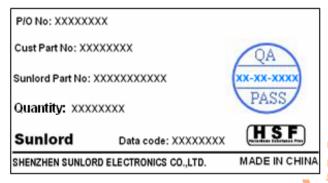
Out case size pleases reefers to Table 9.2.3-2.

- a). Manufacturer: Sunlord ID:
 - "Shenzhen Sunlord Electronics Co., Ltd."
- b). Packing label include the following:
 - i) Customer
 - ii) Manufacturer
 - iii) Date code
 - iv) C/No.

Example; "1/10" means that this case is the 1st of total 10 cases

- v) P/O No.
- vi) Customer Part No.
- vii) Sunlord Part No.
- viii) Quantity.
- ix) Inspection Stamp.





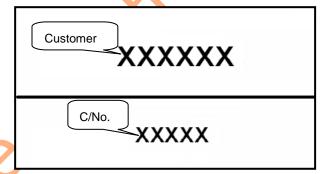


Fig.9.2.3-5

Fig.9.2.3-6

10 Visual inspection standard of product

10 Vis	ile No: Applied to Wire Wound SMD Power Inductor Series		Wound SMD Power Inductor Series	REV:01
Effective	e date:	, дрима то типо тошна отполницион.		KEV.01
No.	Defect Item	Graphic	Rejection identification	Acceptance
1	Core defect	NVI D	The defect length/width (I and w) more than L/6 and W/6, NG.	AQL=0.065
2	Core crack		Visual cracks, NG.	AQL=0.065
3	Starvation	w w	Resin starved length, <i>I</i> , more than L/2,and IF <i>W</i> > 2mm, resin starved width, <i>w</i> , more than W/2, NG. IF <i>W</i> ≤ 2mm, resin starved width, <i>w</i> , don't control.	AQL=0.065
4	Excessive glue		The length, width or height of product beyond specified value, NG.	AQL=0.065
5	Cold solder		Cold solders / more than1mm, NG.	AQL=0.065
6	Solder icicle	H	 The height <i>H</i> of product beyond specified value, NG; The clearance Δf beyond specified value listed in Item 5, NG; 	AQL=0.065
7	Electrode uneven	h	The clearance Δf beyond specified value listed in Item 5 , NG;	AQL=0.065
8	Marking defect	L1 a	The content of marking 1) is indistinct, 2) disagrees with current product P/N requirements, NG; Intersection angle by L1 and L2 more than 45°, NG.	AQL=0.065

11 Recommended Soldering Technologies

11.1Re-flowing Profile:

△ Preheat condition: 150 ~200 °C/60~120sec.

△ Allowed time above 217°C: 60~90sec.

△ Max temp: 260°C

△ Max time at max temp: 5sec.
 △ Solder paste: Sn/3.0Ag/0.5Cu
 △ Allowed Reflow time: 2x max
 Please refer to Fig. 11.1-1.

[Note: The reflow profile in the above table is only for qualification and is not meant to specify board assembly profiles. Actual board assembly profiles must be based on the customer's specific board design, solder paste and process, and should not exceed the parameters as the Reflow profile shows.]

11.2 Iron Soldering Profile:

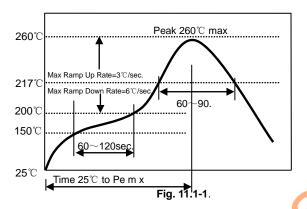
△ Iron soldering power: Max. 30W

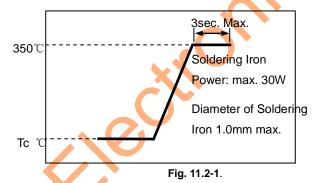
△ Pre-heating: 150°C/60sec.

△ Soldering Tip temperature: 350°C Max.

△ Soldering time: 3sec. Max.
 △ Solder paste: Sn/3.0Ag/0.5Cu
 △ Max.1 times for iron soldering
 Please refer to Fig. 11.2-1.

[Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.]





12 Precautions

12.1 Surface mounting

- Mounting and soldering condition should be checked beforehand.
- Applicable soldering process to this product is reflow soldering only.
- Recommended conditions for repair by soldering iron:

Preheat the circuit board with product to repair at 150°C for about 1 minute.

Put soldering iron on the land-pattern.

Soldering iron's temperature: 350 °C maximum/Duration: 3 seconds maximum/1 time for each terminal.

The soldering iron should not directly touch the inductor.

Product once removes from the circuit board may not be used again.

12.2 Handing

- Keep the products away from all magnets and magnetic objects.
- Be careful not to subject the products to excessive mechanical shocks.
- Please avoid applying impact to the products after mounted on pc board.
- Avoid ultrasonic cleaning.

12.3 Storage

- To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled.
- Recommended conditions: -10°C~40°C, 70%RH (Max.)
- Even under ideal storage conditions, solderability of products electrodes may decrease as time passes. For this reason, product should be used with one year from the time of delivery.
- In case of storage over 6 months, solderability shall be checked before actual usage.

12.4 Regarding Regulations

- Any Class- I or Class-II ozone-depleting substance (ODS) listed in the Clean Air Act in US for regulation is not included in the products or applied to the products at any stage of whose manufacturing processes.
- Certain brominated flame retardants (PBBs,PBDEs) are not used at all.
- The products of this specification are not subject to the Export Trade Control Order in China or the Export Administration Regulations in US.

- The guaranteed operating conditions of the products are in accordance with the conditions specified in this specification.
- Please note that Sunlord takes no responsibility for any failure and/or abnormality which is caused by use under other than the aforesaid operating conditions.

Categories: general confidential

12.6 Please make sure to record the lot number on the label when using Sunlord's products in order for good traceability.

